

CHENMKO ENTERPRISE CO., LTD

SURFACE MOUNT

Lead free devices SCHOTTKY BARRIER RECTIFIER VOLTAGE RANGE 70 - 100 Volts CURRENT 2.0 Amperes

FEATURES

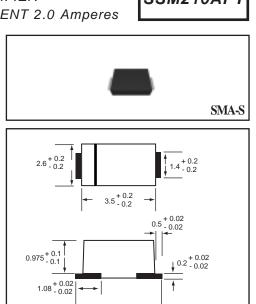
- Plastic package has Underwriters Laboratory
- Flammability Classification 94V-0 For surface mounted applications
- Low profile package
- Built-in strain relief
- * Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- High current capability, low forward voltage drop
- High surge capability *
- For use in low voltage high frequency inverters, free wheeling, and polarity protection applications High temperature soldering guaranteed :
- 260°C/10 seconds at terminals

MECHANICAL DATA

Case: JEDEC SMA-S molded plastic Terminals: Solder plated, solderable per MIL-STD-750, Method 2026 Polarity: Color band denotes cathode end

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.



4.5 + 0.2

Dimensions in millimeters

MAXIMUM RATINGES (At TA = 25°C unless otherwise noted)

RATINGS	SYMBOL	SSM27APT	SSM28APT	SSM29APT	SSM210APT	UNITS
Maximum Recurrent Peak Reverse Voltage	Vrrm	70	80	90	100	Volts
Maximum RMS Voltage	Vrms	49	56	63	70	Volts
Maximum DC Blocking Voltage	VDC	70	80	90	100	Volts
Maximum Average Forward Rectified Current	lo	2.0				
Peak Forward Surge Current 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	IFSM	50				
Typical Junction Capacitance (Note 2)	CJ	110				
Typical Thermal Resistance (Note 1)	RθJL	48				°C/W
Operating and Storage Temperature Range	TJ,TSTG	-65 to +150				°C

ELECTRICAL CHARACTERISTICS (At TA = 25°C unless otherwise noted)

CHARACTERISTICS		SYMBOL	SSM27APT	SSM28APT	SSM29APT	SSM210APT	UNITS
Maximum Instantaneous Forward Voltage at 2.0 A DC		VF	0.75		0.80		Volts
Maximum Average Reverse Current	@ TA = 25°C	la la	0.5				mAmps
at Rated DC Blocking Voltage	@ TA = 100°C	l R	10				
NOTES: 1 Thermal Resistance (Junction to Lead): PC Roard Mounted on 0.2 X 0.2" (.5 X Smm.) conner ned area							2004-12

NOTES: 1. Thermal Resistance (Junction to Lead): PC Board Mounted on 0.2 X 0.2" (5 X 5mm) copper pad area. 2. Measured at 1.0 MHz and applied reverse voltage of 4.0 volts.



SSM27APT

SSM210APT

SMA-S

